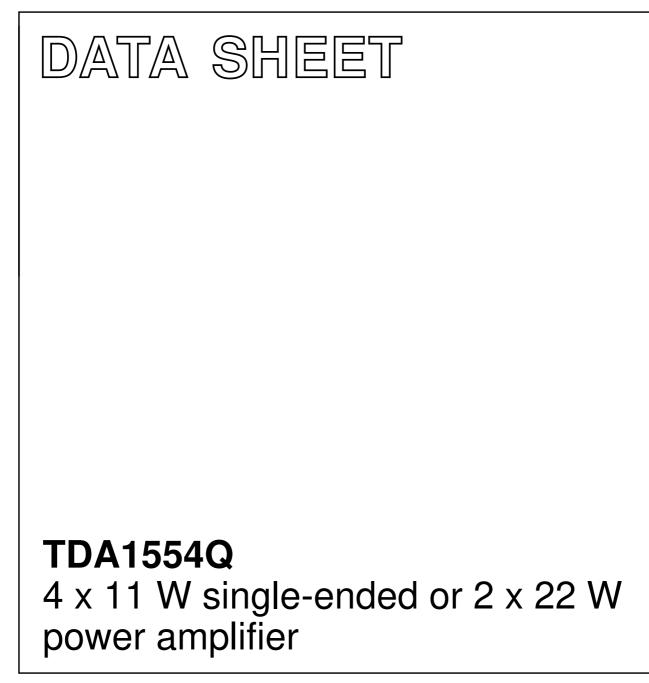
INTEGRATED CIRCUITS



Product specification File under Integrated Circuits, IC01 May 1992



GENERAL DESCRIPTION

The TDA1554Q is an integrated class-B output amplifier in a 17-lead single-in-line (SIL) plastic power package. The circuit contains 4×11 W single-ended or 2×22 W bridge amplifiers. The device is primarily developed for car radio applications.

Features

- Requires very few external components
- Flexibility in use Quad single-ended or stereo BTL
- High output power
- Low offset voltage at outputs (important for BTL)
- Fixed gain
- Good ripple rejection
- Mute/stand-by switch
- Load dump protection
- AC and DC short-circuit-safe to ground and V_{P}

- Thermally protectedReverse polarity safe
- Capability to handle high energy on outputs $(V_P = 0 V)$
- Protected against electrostatic discharge
- No switch-on/switch-off plop
- Low thermal resistance
- Identical inputs (inverting and non-inverting)
- Flexible leads.

QUICK REFERENCE DATA

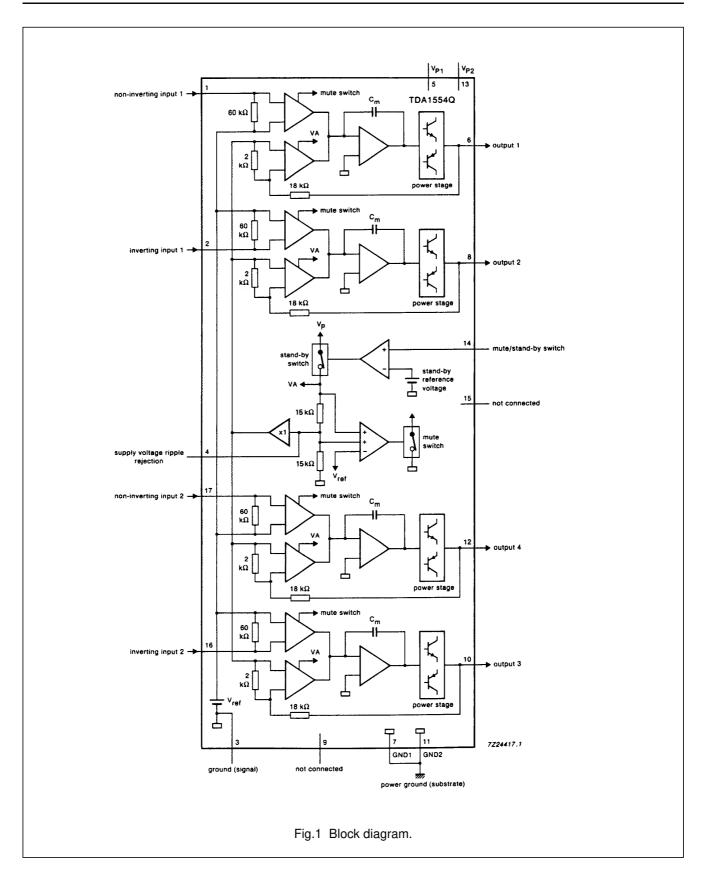
PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage range						
operating		V _P	6.0	14.4	18.0	V
Repetitive peak output current		I _{ORM}	_	_	4	А
Total quiescent current		I _{tot}	-	80	160	mA
Stand-by current		I _{sb}	_	0.1	100	μA
Stereo BTL application						
Output power	$R_L = 4 \Omega$; THD = 10%	Po	20	22	_	w
Supply voltage ripple rejection		RR	48	_	_	dB
Noise output voltage						
(RMS value)	$R_{S} = 0 \Omega$	V _{no(rms)}	_	70	_	μV
Input impedance		Z _I	25	30	38	kΩ
DC output offset voltage		$ \Delta V_0 $	_	_	100	mV
Quad single-ended application						
Output power	THD = 10%					
	$R_L = 4 \Omega$	Po	_	6	_	w
	$R_L = 2 \Omega$	Po	-	11	-	W
Supply voltage ripple rejection		RR	48	_	_	dB
Noise output voltage						
(RMS value)	$R_{S} = 0 \Omega$	V _{no(rms)}	-	50	_	μV
Input impedance		Z _I	50	60	75	kΩ

PACKAGE OUTLINE

17-lead SIL-bent-to-DIL; plastic power (SOT243R); SOT243-1; 1996 July 23.

TDA1554Q

$4 \ge 11$ W single-ended or $2 \ge 22$ W power amplifier



Product specification

$4 \ge 11$ W single-ended or $2 \ge 22$ W power amplifier

TDA1554Q

PINNING

1	NINV1	non-inverting input 1	9	n.c.	not connected
2	INV1	inverting input 1	10	OUT3	output 3
3	GND	ground (signal)	11	GND2	power ground 2 (substrate)
4	RR	supply voltage ripple rejection	12	OUT4	output 4
5	V _{P1}	positive supply voltage 1	13	V _{P2}	positive supply voltage 2
6	OUT1	output 1	14	M/SS	mute/stand-by switch
7	GND1	power ground 1 (substrate)	15	n.c.	not connected
8	OUT2	output 2	16	INV2	inverting input 2
			17	NINV2	non-inverting input 2

FUNCTIONAL DESCRIPTION

The TDA1554Q contains four identical amplifiers with differential input stages (two inverting and two non-inverting) and can be used for single-ended or bridge applications. The gain of each amplifier is fixed at 20 dB (26 dB in BTL). A special feature of this device is:

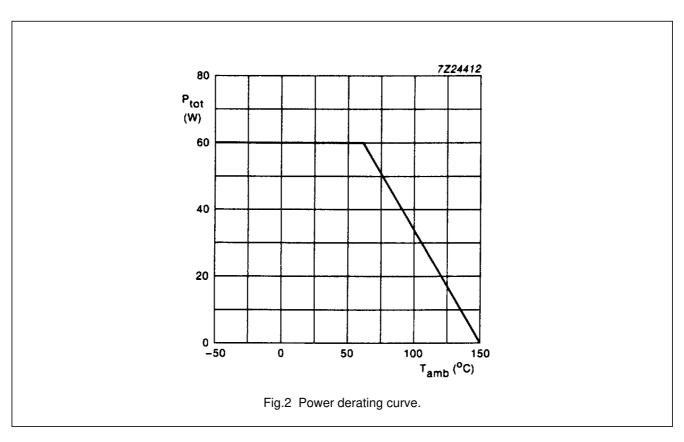
Mute/stand-by switch

- low stand-by current (< 100 μ A)
- low mute/stand-by switching current (low cost supply switch)
- mute facility

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

PARAMETER	CONDITIONS	SYMBOL	MIN.	MAX.	UNIT
Supply voltage					
operating		V _P	-	18	V
non-operating		V _P	_	30	V
load dump protected	during 50 ms;				
	t _r ≥ 2.5 ms	V _P	-	45	V
Non-repetitive peak output current		I _{OSM}	_	6	A
Repetitive peak output current		I _{ORM}	-	4	A
Storage temperature range		T _{stg}	-55	+ 150	°C
Junction temperature		Tj	_	150	°C
AC and DC short-circuit-safe voltage		V _{PSC}	-	18	V
Energy handling capability at outputs	$V_{P} = 0 V$		-	200	mJ
Reverse polarity		V _{PR}	-	6	V
Total power dissipation	see Fig.2	P _{tot}	_	60	w



DC CHARACTERISTICS

 V_P = 14.4 V; T_{amb} = 25 °C; measurements taken using Fig.4; unless otherwise specified

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply						
Supply voltage range	note 1	V _P	6.0	14.4	18.0	V
Total quiescent current		I _{tot}	-	80	160	mA
DC output voltage	note 2	Vo	_	6.9	-	V
DC output offset voltage		$ \Delta V_O $	-	-	100	mV
Mute/stand-by switch						
Switch-on voltage level		V _{ON}	8.5	_	_	V
Mute condition		V _{mute}	3.3	-	6.4	V
Output signal in mute	V _I = 1 V (max);					
position	f = 1 kHz	Vo	_	_	2	mV
DC output offset voltage						
(between pins 6 to 8 and 10 to 12)		$ \Delta V_O $	-	-	100	mV
Stand-by condition		V _{sb}	0	-	2	V
DC current in						
stand-by condition		I _{sb}	_	_	100	μA
Switch-on current		I _{sw}	-	12	40	μA

TDA1554Q

AC CHARACTERISTICS

 $V_P = 14.4 \text{ V}$; $R_L = 4 \Omega$; f = 1 kHz; $T_{amb} = 25 \text{ °C}$; measurements taken using Fig.3 for stereo BTL application and Fig.4 for quad single-ended application unless otherwise specified

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Stereo BTL application						
Output power	THD = 0.5%	Po	15	17	-	W
	THD = 10%	Po	20	22	_	W
Output power at $V_P = 13.2 V$	THD = 0.5%	Po	_	12	_	W
	THD = 10%	Po	_	17	_	W
Total harmonic distortion	P _o = 1 W	THD	_	0.1	_	%
Power bandwidth	THD = 0.5%					
	$P_o = -1 dB$					
	w.r.t. 15 W	B _w	-	20 to	_	Hz
				15 000		
Low frequency roll-off	note 3					
	–1 dB	fL	-	45	-	Hz
High frequency roll-off	–1 dB	f _H	20	-	-	kHz
Closed loop voltage gain		G _v	25	26	27	dB
Supply voltage ripple rejection	note 4					
ON		RR	48	-	-	dB
mute		RR	48	-	-	dB
stand-by		RR	80	-	-	dB
Input impedance		Z _i	25	30	38	kΩ
Noise output voltage						
(RMS value)						
ON	$R_S = 0 \Omega$; note 5	V _{no(rms)}	-	70	-	μV
ON	R _S = 10 kΩ; note 5	V _{no(rms)}	-	100	200	μV
mute	notes 5 and 6	V _{no(rms)}	-	60	-	μV
Channel separation	$R_S = 10 \text{ k}\Omega$	α	40	-	-	dB
Channel unbalance		∆G _v	-	-	1	dB

TDA1554Q

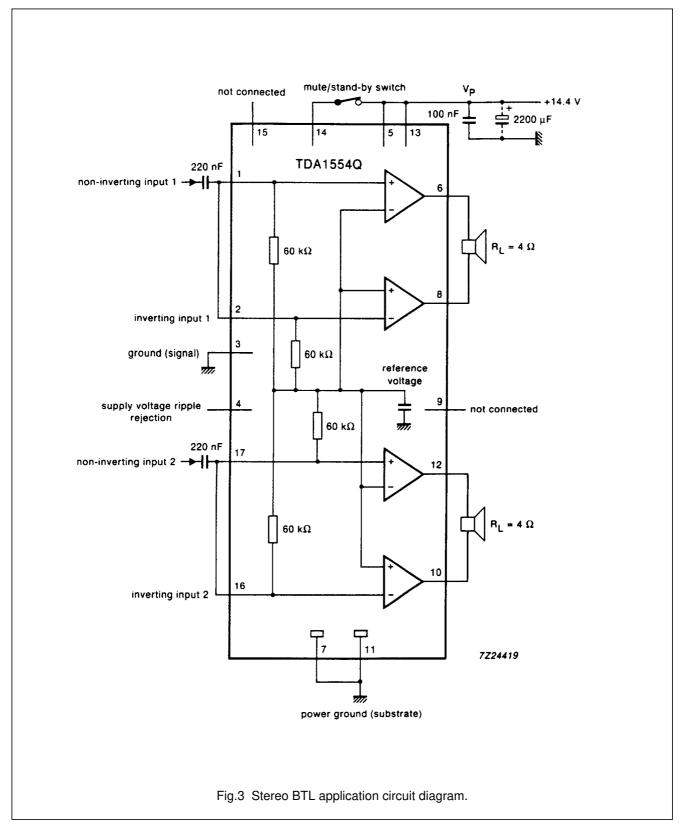
PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Quad single-ended application						
Output power	note 7					
	THD = 0.5%	Po	4	5	_	W
	THD = 10%	Po	5.5	6	_	W
Output power at $R_L = 2 W$	note 7					
	THD = 0.5%	Po	7.5	8.5	_	W
	THD = 10%	Po	10	11	_	W
Total harmonic distortion	$P_o = 1 W$	THD	_	0.1	_	%
Low frequency roll-off	note 3					
	–3 dB	fL	-	45	_	Hz
High frequency roll-off	–1 dB	f _H	20	_	_	kHz
Closed loop voltage gain		G _v	19	20	21	dB
Supply voltage ripple rejection	note 4					
ON		RR	48	_	_	dB
mute		RR	48	_	_	dB
stand-by		RR	80	_	_	dB
Input impedance		Z _i	50	60	75	kΩ
Noise output voltage						
(RMS value)						
ON	$R_S = 0 \Omega$; note 5	V _{no(rms)}	_	50	_	μV
ON	R _S = 10 kΩ; note 5	V _{no(rms)}	_	70	100	μV
mute	notes 5 and 6	V _{no(rms)}	_	50	_	μV
Channel separation	$R_S = 10 \text{ k}\Omega$	α	40	_	_	dB
Channel unbalance		∆G _v	-	-	1	dB

Notes to the characteristics

- 1. The circuit is DC adjusted at V_P = 6 V to 18 V and AC operating at V_P = 8.5 V to 18 V.
- 2. At 18 V < V_P < 30 V the DC output voltage \leq V_P/2.
- 3. Frequency response externally fixed.
- 4. Ripple rejection measured at the output with a source impedance of 0 Ω (maximum ripple amplitude of 2 V) and a frequency between 100 Hz and 10 kHz.
- 5. Noise voltage measured in a bandwidth of 20 Hz to 20 kHz.
- 6. Noise output voltage independent of $R_S (V_I = 0 V)$.
- 7. Output power is measured directly at the output pins of the IC.

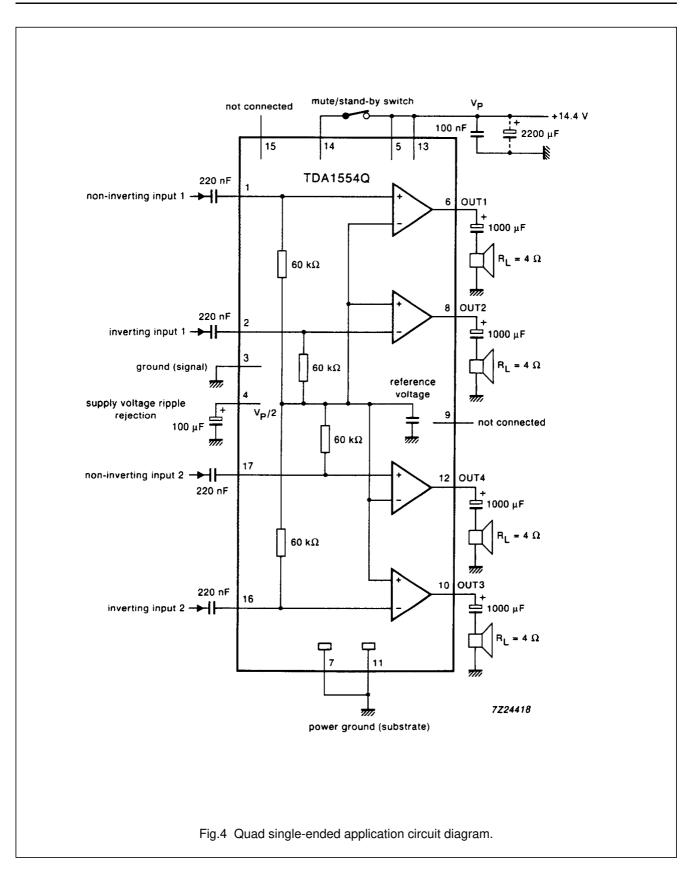
4×11 W single-ended or 2×22 W power amplifier

APPLICATION INFORMATION



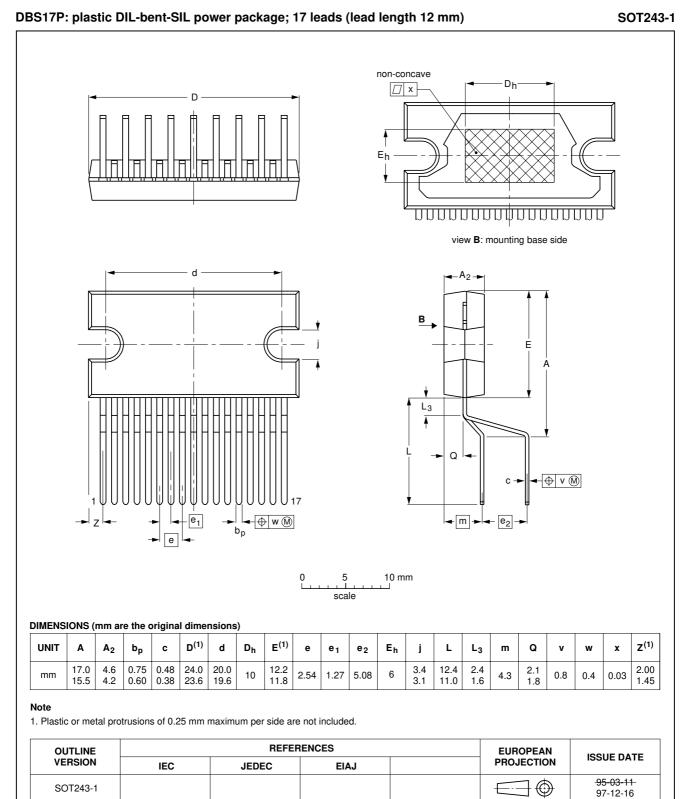
TDA1554Q

$4 \ge 11$ W single-ended or $2 \ge 22$ W power amplifier



May 1992

PACKAGE OUTLINE



SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 $^{\circ}$ C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status			
Objective specification	This data sheet contains target or goal specifications for product development.		
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.		
Product specification	This data sheet contains final product specifications.		
Limiting values			
more of the limiting values of the device at these or at	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or may cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification limiting values for extended periods may affect device reliability.		
Application information			
Where application information is given, it is advisory and does not form part of the specification.			

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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